N-Channel Enhancement Mode MOSFET

Features

- Low RDS(ON)
- Low Miller Charge
- Halogen and Antimony Free(HAF), RoHS compliant

Application

- Motor/Body Load Control
- Load Switch
- DC-DC converters and Off-line UPS

Key Parameters

Parameter	Value	Unit	
BV _{DSS}	30	V	
D Max	3.1 @ V _{GS} = 10 V	mΩ	
R _{DS(ON)} Max	4.2 @ V _{GS} = 4.5 V	mΩ	
V _{GS(th)} typ	1.5	V	
Q _g typ	79 @ V _{GS} = 10 V	nC	

Absolute Maximum Ratings (at Ta = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain-Source Voltage	V _{DS}	30	V	
Gate-Source Voltage	V _{GS}	± 20	V	
Continuous Drain Current	lo	68 43	А	
Peak Drain Current, Pulsed ¹⁾	I _{DM}	210	A	
Avalanche Current	I _{AS}	40	А	
Single Pulse Avalanche Energy 2)	Eas	80	mJ	
Power Dissipation	T _c = 25°C T _c = 100°C	PD	34.7 13.8	W
Operating Junction and Storage Tempera	TJ, Tstg	- 55 to + 150	°C	

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Case	Rejc	3.6	°C/W
Thermal Resistance from Junction to Ambient ³⁾	Reja	50	°C/W

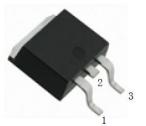
¹⁾ Pulse Test: Pulse Width \leq 100 µs, Duty Cycle \leq 2%, Repetitive rating, pulse width limited by junction temperature T_{J(MAX)} = 150°C.

²⁾ Limited by $T_{J(MAX)}$, starting $T_J = 25 \text{ °C}$, L = 0.1 mH, $R_g = 25 \Omega$, $I_D = 40 \text{ A}$, $V_{GS} = 10 \text{ V}$.

³⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.



Drain Gate



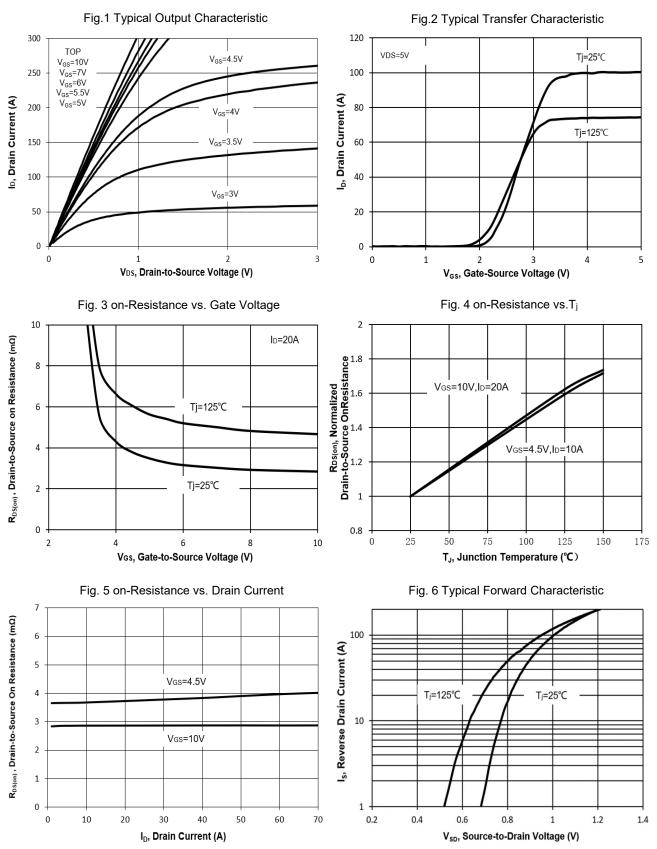
1.Gate 2.Drain 3.Source TO-252 Plastic Package

Characteristics at Ta = 25°C unless otherwise specified

Parameter	Symbol	Min.	Тур.	Max.	Unit
STATIC PARAMETERS			1	1	
Drain-Source Breakdown Voltage at $I_D = 250 \ \mu A$	BV _{DSS}	30	-	-	V
Drain-Source Leakage Current at V _{DS} = 24 V	IDSS	-	-	1	μA
Gate Leakage Current at V_{GS} = ± 20 V	lgss	-	-	± 100	nA
Gate-Source Threshold Voltage at V _{DS} = V _{GS} , I _D = 250 µA	V _{GS(th)}	1.2	-	2.5	V
Drain-Source On-State Resistance at V_{GS} = 10 V, I_D = 20 A at V_{GS} = 4.5 V, I_D = 10 A	R _{DS(on)}	-	2.4	3.1 4.2	mΩ
DYNAMIC PARAMETERS					
Gate resistance at V_{DS} = 0 V, f = 1 MHz	Rg	-	0.6	-	Ω
Forward Transconductance at V_{DS} = 5 V, I_D = 20 A	g fs	-	38	-	S
Input Capacitance at V_{GS} = 0 V, V_{DS} = 15 V, f = 1 MHz	C _{iss}	-	3652	-	pF
Output Capacitance at V_{GS} = 0 V, V_{DS} = 15 V, f = 1 MHz	Coss	-	430	-	pF
Reverse Transfer Capacitance at V_{GS} = 0 V, V_{DS} = 15 V, f = 1 MHz	Crss	-	353	-	pF
Gate charge total at V_{DS} = 15 V, I_D = 20 A, V_{GS} = 10 V at V_{DS} = 15 V, I_D = 20 A, V_{GS} = 4.5 V	Qg	-	79 40	-	nC
Gate to Source Charge at V_{DS} = 15 V, I_D = 20 A, V_{GS} = 10 V	Qgs	-	9.5	-	nC
Gate to Drain Charge at V_{DS} = 15 V, I_D = 20 A, V_{GS} = 10 V	Q _{gd}	-	20	-	nC
Turn-On Delay Time at V _{GS} = 10 V, V _{DS} = 15 V, I _D = 10 A, R _g = 3.3Ω	t _{d(on)}	-	25.6	-	nS
Turn-On Rise Time at V _{GS} = 10 V, V _{DS} = 15 V, I _D = 10 A, R _g = 3.3 Ω	tr	-	35	-	nS
Turn-Off Delay Time at V _{GS} = 10 V, V _{DS} = 15 V, I _D = 10 A, R _g = 3.3 Ω	$t_{d(off)}$	-	25	-	nS
Turn-Off Fall Time at V _{GS} = 10 V, V _{DS} = 15 V, I _D = 10 A, R _g = 3.3Ω	t _f	-	4.8	-	nS
Body-Diode PARAMETERS			i .	i	
Drain-Source Diode Forward Voltage at Is = 1 A, V _{GS} = 0 V	V _{SD}	-	0.7	1.2	V
Body-Diode Continuous Current	ls	-	-	68	Α
Body-Diode Continuous Current, Pulsed	lsм	-	-	210	Α
Body Diode Reverse Recovery Time at I _S = 10 A, di/dt = 100 A / μs	t _{rr}	-	17	-	nS
Body Diode Reverse Recovery Charge at $I_S = 10 \text{ A}$, di/dt = 100 A / μ s	Qrr	-	7.5	-	nC



Electrical Characteristics Curves

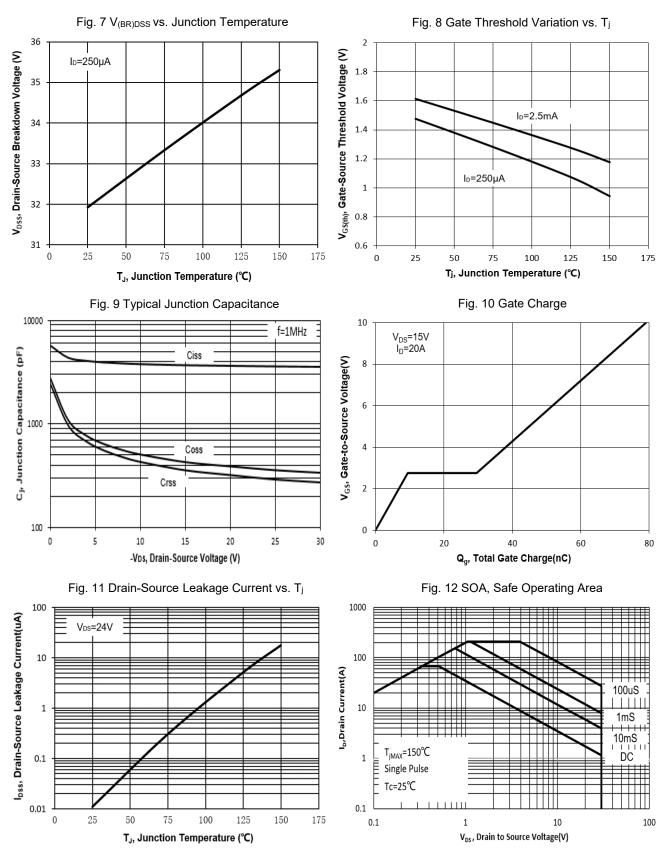




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Electrical Characteristics Curves





0.001 0.000001

0.00001

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Electrical Characteristics Curves

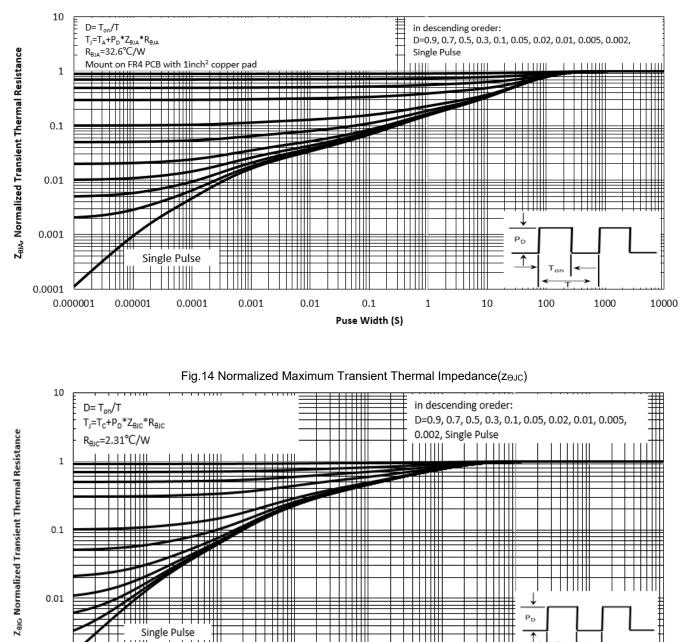


Fig.13 Normalized Maximum Transient Thermal Impedance(z_{OJA})

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1 т

10

100

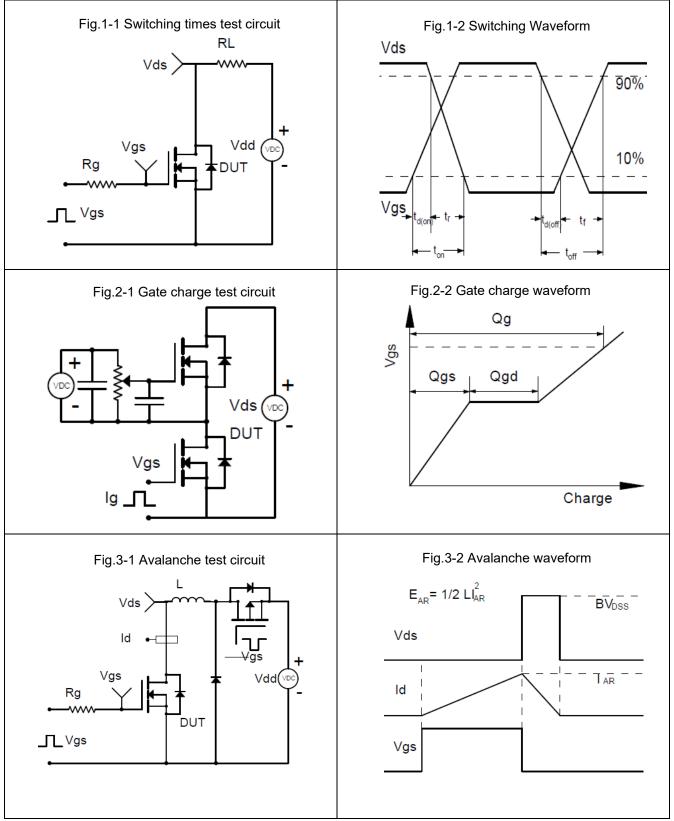
1

0.01

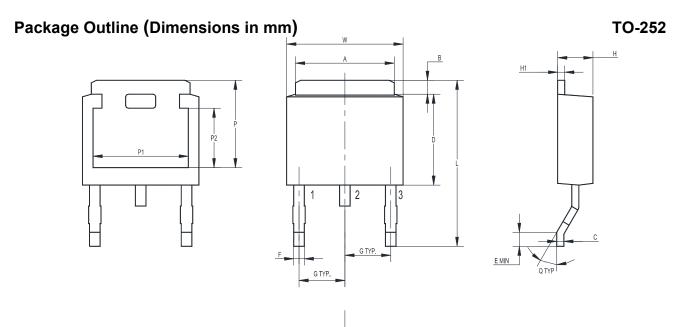
Puse Width(S)

0.1

Test Circuits

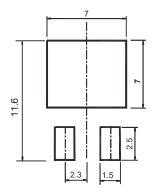






UNIT	Α	В	С	D	Е	F	G	W	Н	H1	Q	L	Р	P1	P2
	5.5	1.20	0.65	6.2	0.8	1.0	2.3	6.7	2.5	0.65	60°	10.7	5.4	5.0	3.4
mm	4.9	0.85	0.4	5.6	MIN	0.5	TYP	6.1	2.1	0.4	TYP	9	5.0	4.6	2.9

Recommended Soldering Footprint



Packing information

Dookaga	Package Tape Width (mm)		tch	Reel	Size	Per Reel Packing Quantity	
гаскауе			inch	mm	inch	Fer Reel Facking Quantity	
TO-252	12	8 ± 0.1	0.315 ± 0.004	330	13	2,500	

Marking information

- " TR03N030LS " = Part No.
- " ****** " = Date Code Marking

Font type: Arial





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